

Fair-Rite P/N **2773008111**

73 Material Grade

Nominal Chemical Composition

<u>Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)= 0.523	
Fe2O3	1309-37-1	67	0.3504	Compound Weight (g) Breakdown of 73 Material
ZnO	1314-13-2	14	0.0732	
MnO	1344-43-0	19	0.0994	

Pb- Free Plated Round Cu Wire

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of wire (g)= 0.177	
Cu	7440-50-8	94.4	0.16709	Element Weight (g) Breakdown of Pb- Free Plated Round Cu Wire
Plating:				
Ni	7440-02-0	0.9	0.00159	
Sn	7440-31-5	4.7	0.00832	

Calculated Maximum Levels of RoHS Restricted Substances Present in 73 Material Grade

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm)</u>	<u>ppm</u>	Wt of core (g)= 0.523	
Cr+6	1000	0.00	0	RoHS Impurity Substance Weight (g) Breakdown of 73 Material
Cd	100	3.70	1.9351E-06	
Hg	1000	0.10	5.23E-08	
Pb	1000	8.25	4.31475E-06	
PBB	1000	0.00	0	
PBDE	1000	0.00	0	

Supporting notes:

1. P/N 2773008111 consists of:
 - a core 73 Material Grade
 - b wire Pb- Free Plated Round Cu Wire
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels